

Materials Declaration

Package	LFCSP
Body Size	6 X 6 X 0.85 (3.95 mm exposed pad)
LeadCount	36
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	3.63 E-02	392045
Multiaromatic Resin	16.0	6.91 E-03	74678
Subtotal		4.32 E-02	466723

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	4.19 E-02	452572
Fe	2.35	1.03 E-03	11148
Zn	0.12	5.20 E-05	562
P	0.03	1.30 E-05	140
Subtotal		4.30 E-02	464422

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100.0	4.32 E-04	4667

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	1.02 E-03	11051

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.86 E-03	20071

Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.39 E-03	25861

Die Attach Material

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	4.67 E-04	5045
Resin	21.0	1.40 E-04	1512
Metal Oxide	3.0	2.00 E-05	216
Amine	3.0	2.00 E-05	216
Gamma Butyrolactone	3.0	2.00 E-05	216
Subtotal		6.67 E-04	7205

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A13052. ICP-OES.
Cd	Not Detected	EPA Method 3051A13052. ICP-OES.
Hg	Not Detected	EPA Method 3051A13052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/ 3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/ 3550C. GC/MS.

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Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/ 3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/ 3550C. GC/MS.

Package Totals

Weight (g)	PPM
9.26 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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